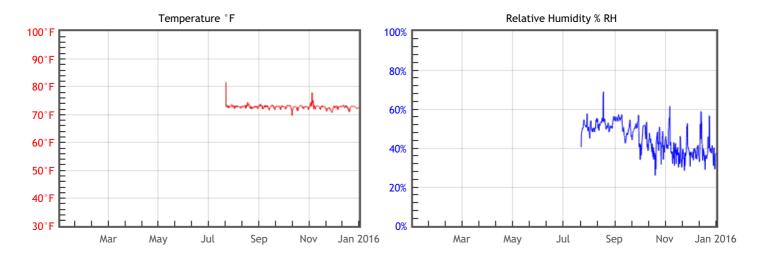
## **DMC North Stacks**

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## **Preservation Environment Evaluation**

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 34	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK  % DC = 0.7  % EMC min = 7.2  % EMC max = 9.7	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD  MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 9.7	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

# Graphs



## **Statistics**

Temperature		Relative Humidity		Dew P	Dew Point	
T°F Mean	72.8	%RH Mean	45	DP°F Mean	49.8	
T°F Median	72.8	%RH Median	45	DP°F Median	50.5	
T°F Stdev	0.7	%RH Stdev	8	DP°F Stdev	4.9	
T°F Min	68.6	%RH Min	23	DP°F Min	33.4	
T°F Max	81.7	%RH Max	71	DP°F Max	66.8	

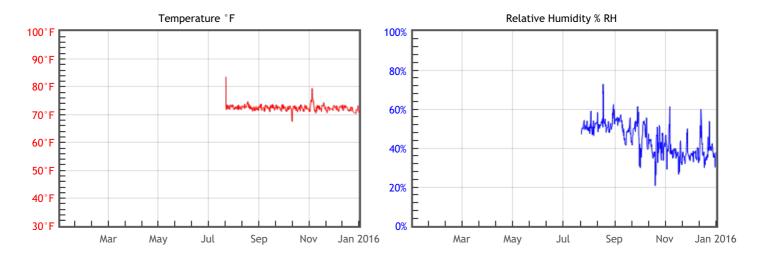
## **DMC South Stacks**

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## **Preservation Environment Evaluation**

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	RISK TWPI = 36	Accelerated rate of chemical decay in all organic materials due to the cumulative effects of temperature and humidity, with especially high risk for fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics.
Mechanical Damage Physical damage to hygroscopic materials	OK  % DC = 0.79  % EMC min = 7.1  % EMC max = 9.9	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 9.9	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

# Graphs



## **Statistics**

Temperature		Relative Humidity		Dew P	Dew Point	
T°F Mean	72.4	%RH Mean	45	DP°F Mean	49.2	
T°F Median	72.3	%RH Median	45	DP°F Median	49.7	
T°F Stdev	1.1	%RH Stdev	8	DP°F Stdev	5.2	
T°F Min	67.3	%RH Min	15	DP°F Min	23.3	
T°F Max	83.6	%RH Max	73	DP°F Max	66.8	